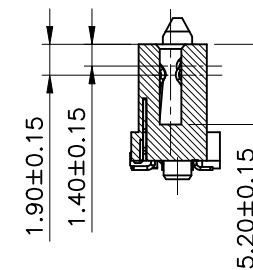
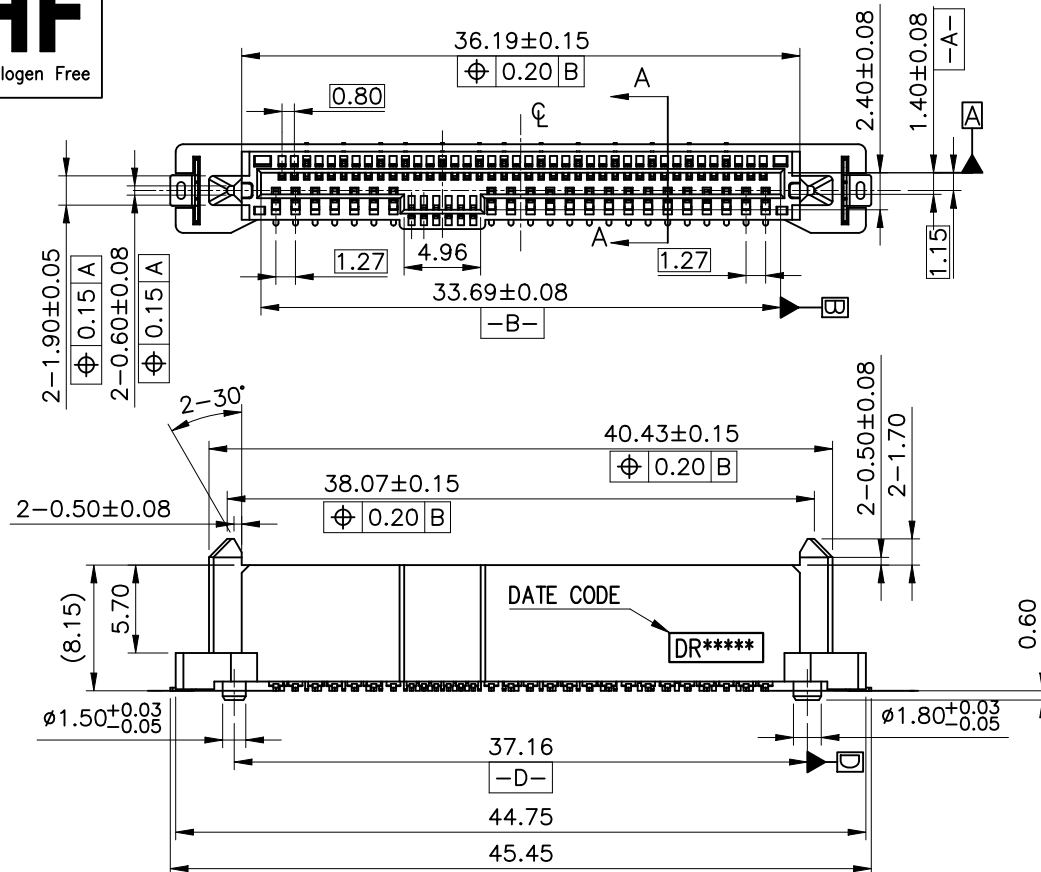
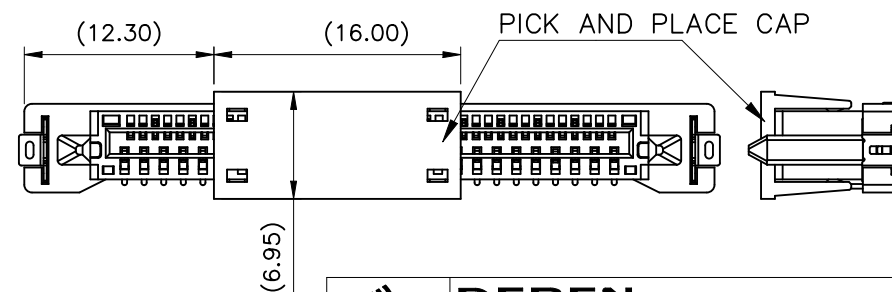
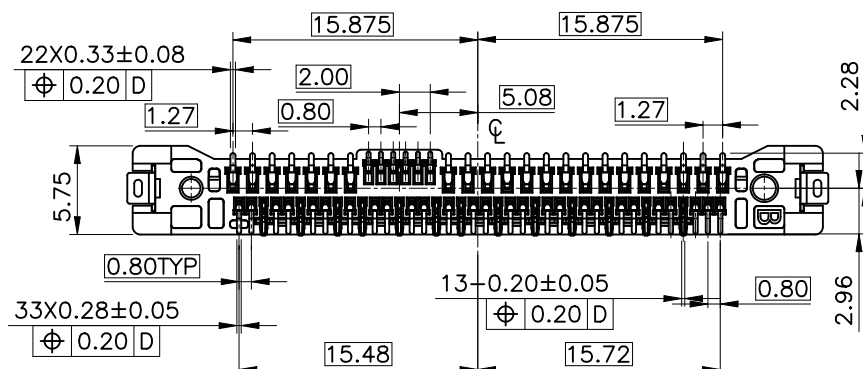
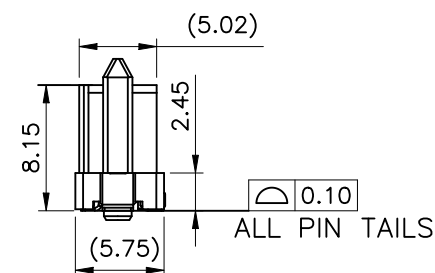


REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A			THE OFFICIAL RELEASE	12/05'24	Winner



SECTION A-A



DIM	TOL	DIM	TOL
x.	± 0.30	x.	$\pm 2^{\circ}$
.x	± 0.25	.x	$\pm 1^{\circ}$
.xx	± 0.20		



DEREN

SHENZHEN DEREN ELECTRONIC CO., LTD

CUSTOMER DRAWING		DATE
DESIGN:	Winner	12/05'24
CHECK:	LFJ	12/05'24
APPROVAL:	Bill	12/05'24

TITLE: PCIE SAS 68PIN 4.0 REC VERTICAL
SMT WITH SMT PEG CONN.

P/N:	562201-003H
------	-------------

SHEET:	1/3		
SCALE:	1:1	UNIT:	mm

HF

Halogen Free

REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
SEE SHEET 1					

NOTES:

1.MATERIAL

- 1.1.HOUSING: HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK;
- 1.2.CAP: HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK;
- 1.3.CONTACT: COPPER ALLOY
- 1.4.PEG: STAINLESS STEEL

2. FINISH:

2.1 CONTACT:

- 0.75um[30u"]MIN, Au PLATING ON CONTACT AREA.
- 2.03um [80u"] MIN. TIN PLATING ON SOLDER TAIL AREA.
- 1.27um [50u"] MIN.NICKEL UNDERPLATING ON ALLOVER AREA.

2.2 PEG

- 2.03um [80u"] MIN TIN PLATING OVERALL
- 1.27um [50u"] MIN NICKEL UNDERPLATING OVERALL

3. ELECTRICAL :

3-1.CONTACT CURRENT RATING :

- CONTINUOUS CURRENT:1.5A
PEAK CURRENT:2.5A for 1.5s

3-2 CONGACT RESISTANCE:40mΩ MAX.(INITIAL)

3-3.OPERATING TEMPERATURE : -55°C TO +85°C

3-4.VOLTAGE:30V MAX.

3-5.INSULATION RESISTANCE :1000 MEGAOHMS MIN.

3-6.DIELECTRIC WITHSTANDING VOLTAGE :400VAC MIN.

3-7.LOW LEVEL CONTACT RESISTANCE :

4.MECHANICAL CHARACTERISTICS :

4-1.INSERTION FORCE :65N MAX.

4-2.DURABILITY :500 MATING CYCLES.

5. APPLIED TO REFLOW SOLDERING PROCESS

6. RECOMMENDED STENCIL THICKNESS: 0.13mm min.

7. PART NUMBER DESCRIPTION:

562201-003H

CONTACT PLATING CODE:

- 0: Au 30u"
1: Au 15u"
2: Gold Flash

LOGO CODE:

- 0: W/ DEREN LOGO
1: W/O LOGO

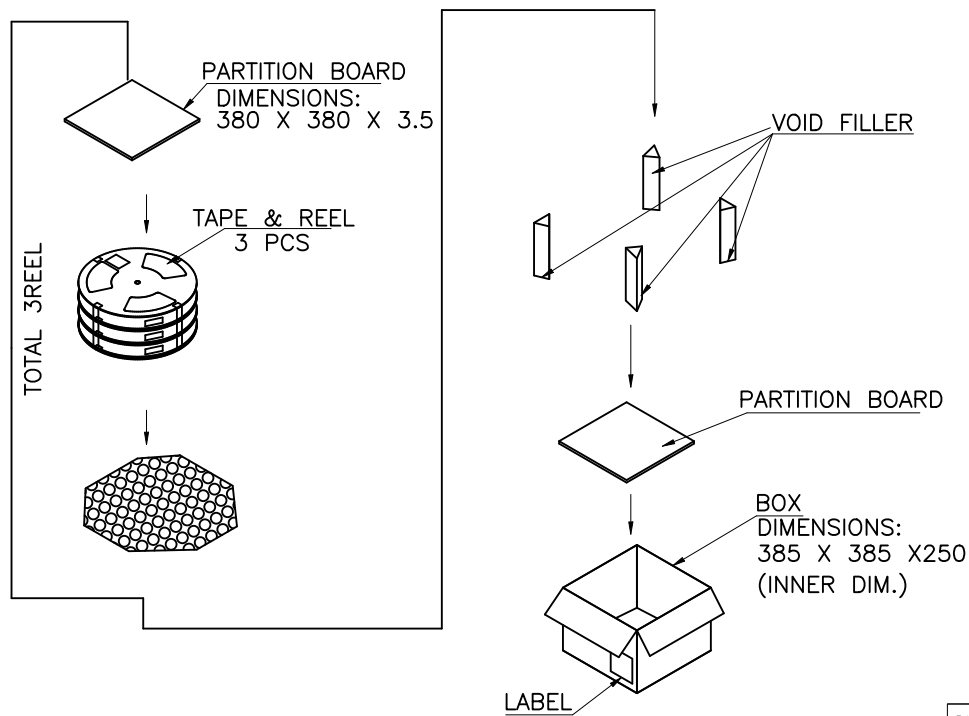
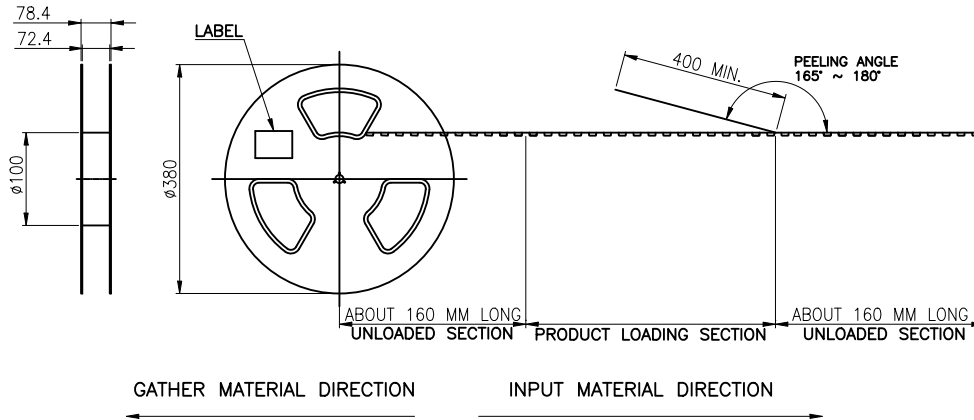
 SOLDER PAD

RECOMMEND P.C.B LAYOUT(COMPONENT SIDE)

TOLERANCES: ±0.05;PCB THICKNESS:1.6mm(TOP VIEW)

DIM	TOL	DIM	TOL		DEREN			
x.	±0.30	x.	±2°		SHENZHEN DEREN ELECTRONIC CO.,LTD			
.x	±0.25	.x	±1°		CUSTOMER DRAWING	DATE	TITLE: PCIE SAS 68PIN 4.0 REC VERTICAL SMT WITH SMT PEG CONN.	
.xx	±0.15				DRAW NO.	DESIGN:	Winner	12/05'24
				SC2410767	CHECK:	LFJ	12/05'24	P/N: 562201-003H
				REV. A	APPROVAL:	Bill	12/05'24	SHEET: 2/3
								SCALE: 1:1
								UNIT: mm

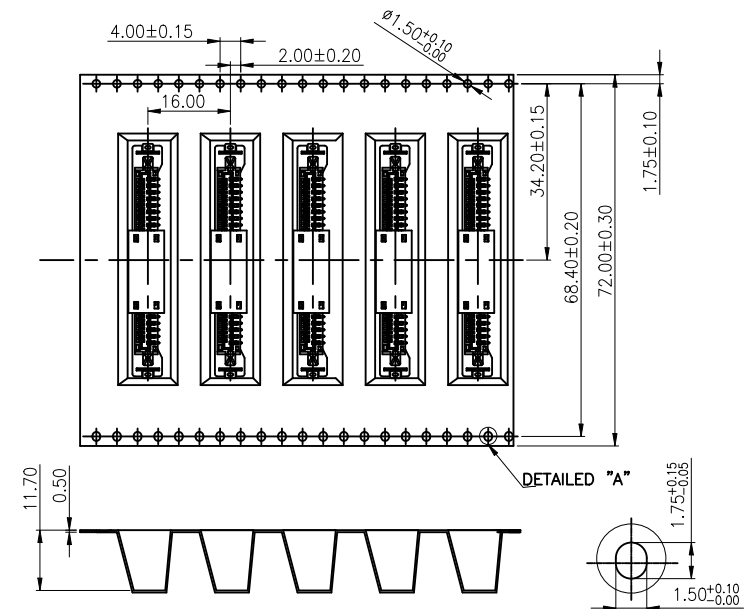
HF
Halogen Free



500	3	1500
PCS/TAPE	REELS/BOX	PCS/BOX

DIM	TOL	DIM	TOL
x	±0.38	x	±2"
.x		.x	±1"
.xx	±0.25		
.xxx	±0.20		

REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
SEE SHEET 1					



- NOTES : (FOR TAPE & REEL)
PACKAGING MATERIAL IN PLASTIC, RUBBER, INK, PIGMENT AND PAINT
MUST MEET DEREN CONTROLLED SUBSTANCES SPEC.
* CADMIUM AND CADMIUM COMPOUNDS NOT TO EXCEED:
5 PPM.
* LEAD, CADMIUM, CHROM VI AND MERCURY NOT TO EXCEED:
100 PPM (COMBINED).
* CARRIER TAPES, COVER TAPES, REELS AND TAPED COMPONENTS
MUST MEET THE REQUIREMENTS DEFINED PER EIA-481-B.
1. MATERIAL :
COVER TAPE : PET, COLOR: CLEAR
CARRIER TAPE : PS
REEL : PS
SHIPPING BOX: CORRUGATED FIBER
 2. DIMENSION :
REEL : SEE DRAWING
BOX : SEE DRAWING
 3. QUANTITY : SEE TABLE
 4. WEIGHT : SEE TABLE
 5. PEELING RESISTANCE : 10gf~100gf (for 8mm)
10gf~130gf (for 12mm~56mm)
10gf~150gf (for 72mm)
 6. PEELING SPEED : 300mm/MINUTES



DEREN

SHENZHEN DEREN ELECTRONIC CO., LTD

CUSTOMER DRAWING	DATE	TITLE: PCIE SAS 68PIN 4.0 REC VERTICAL SMT WITH SMT PEG CONN.
DESIGN: Winner	12/05'24	P/N: 562201-003H
CHECK: LFJ	12/05'24	SHEET: 3/3
APPROVAL: Bill	12/05'24	SCALE: N/A UNIT: mm